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Agenda

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Cypress becomes part of Infineon

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Industrial Power Control

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Power & Sensor Systems

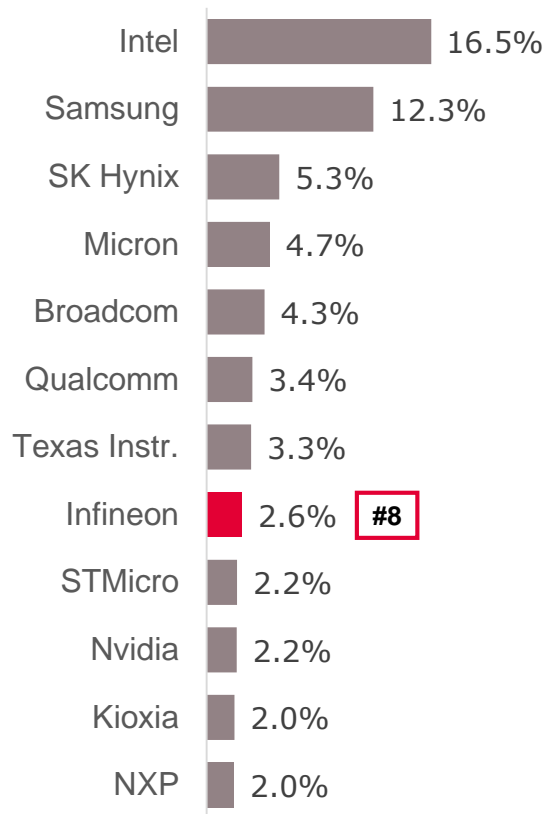
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ESG: targets & achievements

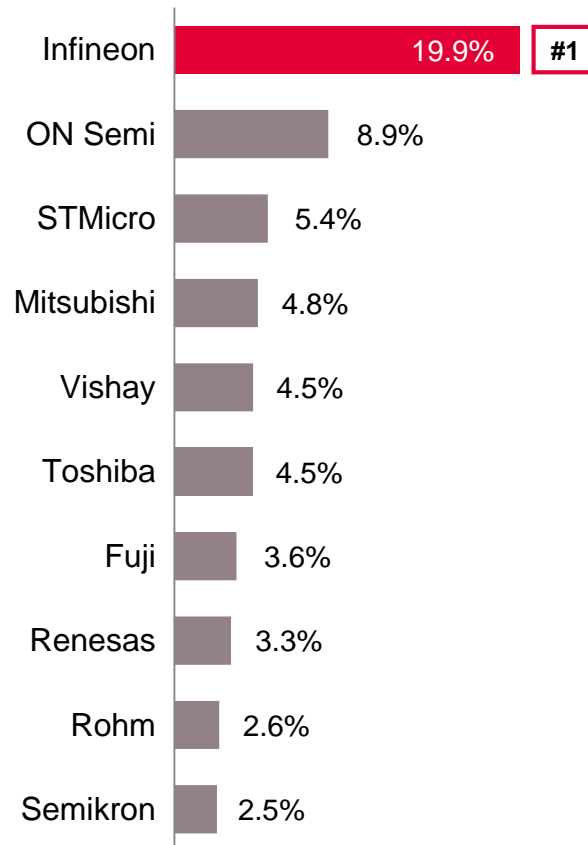
Infineon and Cypress create a global top-10 player, and the new #3 in the overall microcontroller market



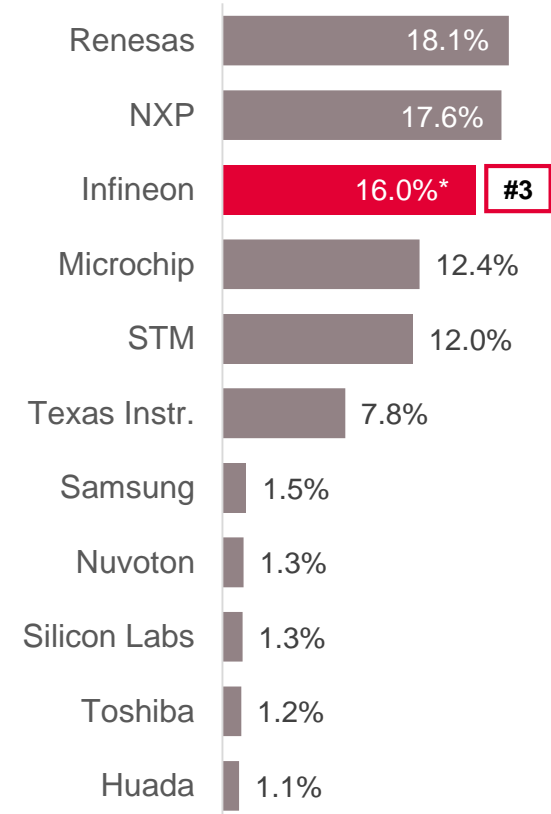
Semiconductor suppliers 2019 total market: \$428bn¹⁾



Power discretes and modules 2018 total market: \$21.0bn²⁾



MCU suppliers 2019 total market: \$17.5bn¹⁾



* pro forma figure

1) Based on or includes research from Omdia, "Annual 2001-2019 Semiconductor Market Share Competitive Landscaping Tool – Q4 2019 v2", March 2020.

2) Based on or includes research from Omdia, "Power Semiconductor Market Share Database – 2018", September 2019.

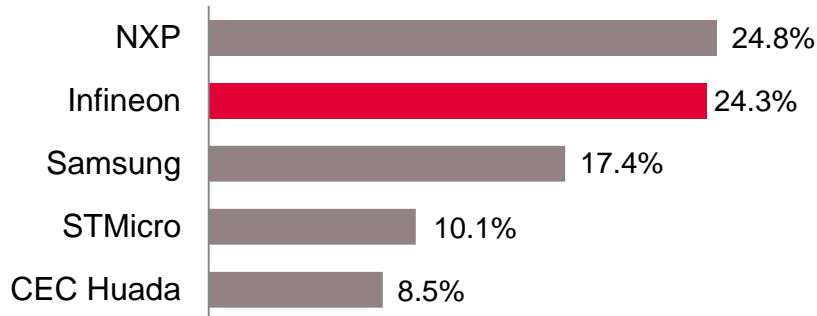
Results are not an endorsement of Infineon Technologies AG. Any reliance on these results is at the third party's own risk.

Infineon remains top player in its target markets: security ICs, NOR Flash, and MEMS microphones



Security ICs

2018 total market: \$3.2bn

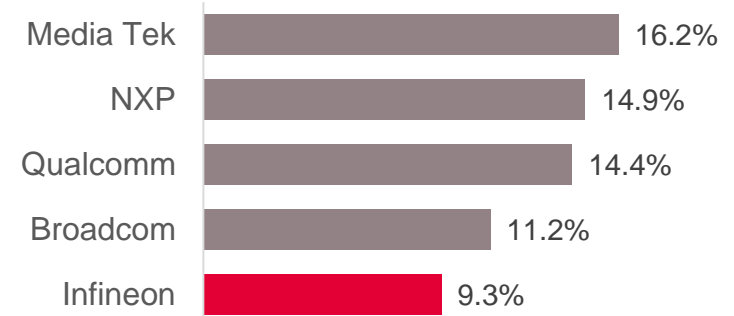


ABI Research, "Smart card & secure ICs", September 2019

Wi-Fi standalone ICs

2018 total market: 917m units

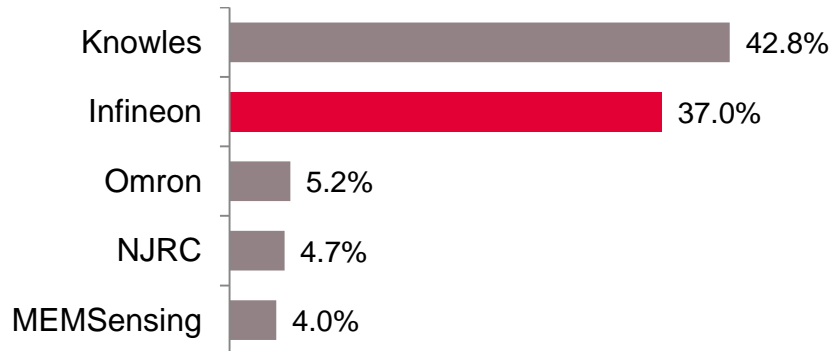
Infineon is focusing on wearables and IoT but not addressing routers, PCs, notebooks, tablets.



ABI Research, "Wireless Connectivity Technology Segmentation and Addressable Markets", November 2019.

MEMS microphones die supplier

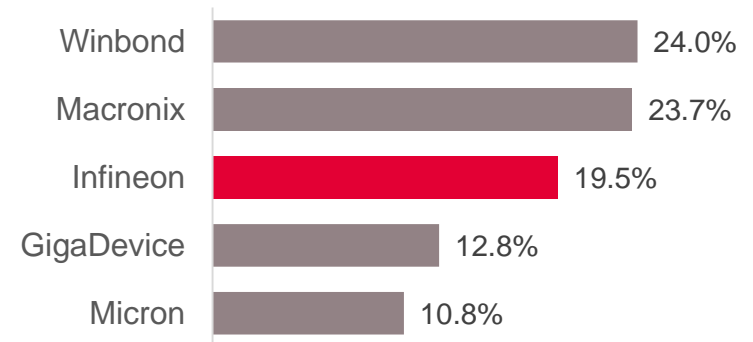
2018 total market: 4.6bn units



Based on or includes research from Omdia, "MEMS Microphone Database 2019", January 2020.

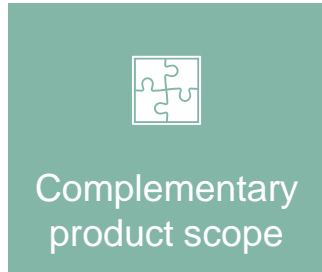
NOR Flash

2019 total market: \$2.2bn



Based on or includes research from Omdia, "Annual 2001-2019 Semiconductor Market Share Competitive Landscaping Tool – Q4 2019 v2", March 2020.

Two complementary companies in many aspects form a financially stronger and more balanced player

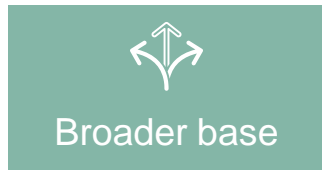


*power management
security solutions
sensor systems*

**System solution
leader in high-growth
markets: automotive,
industrial and IoT**



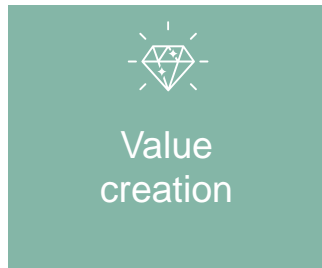
*MCUs
connectivity
low power
differentiated memories
software / eco-system*



- › more structural growth drivers
- › more balanced geographical mix
- › enlarged customer base
- › higher share of distribution

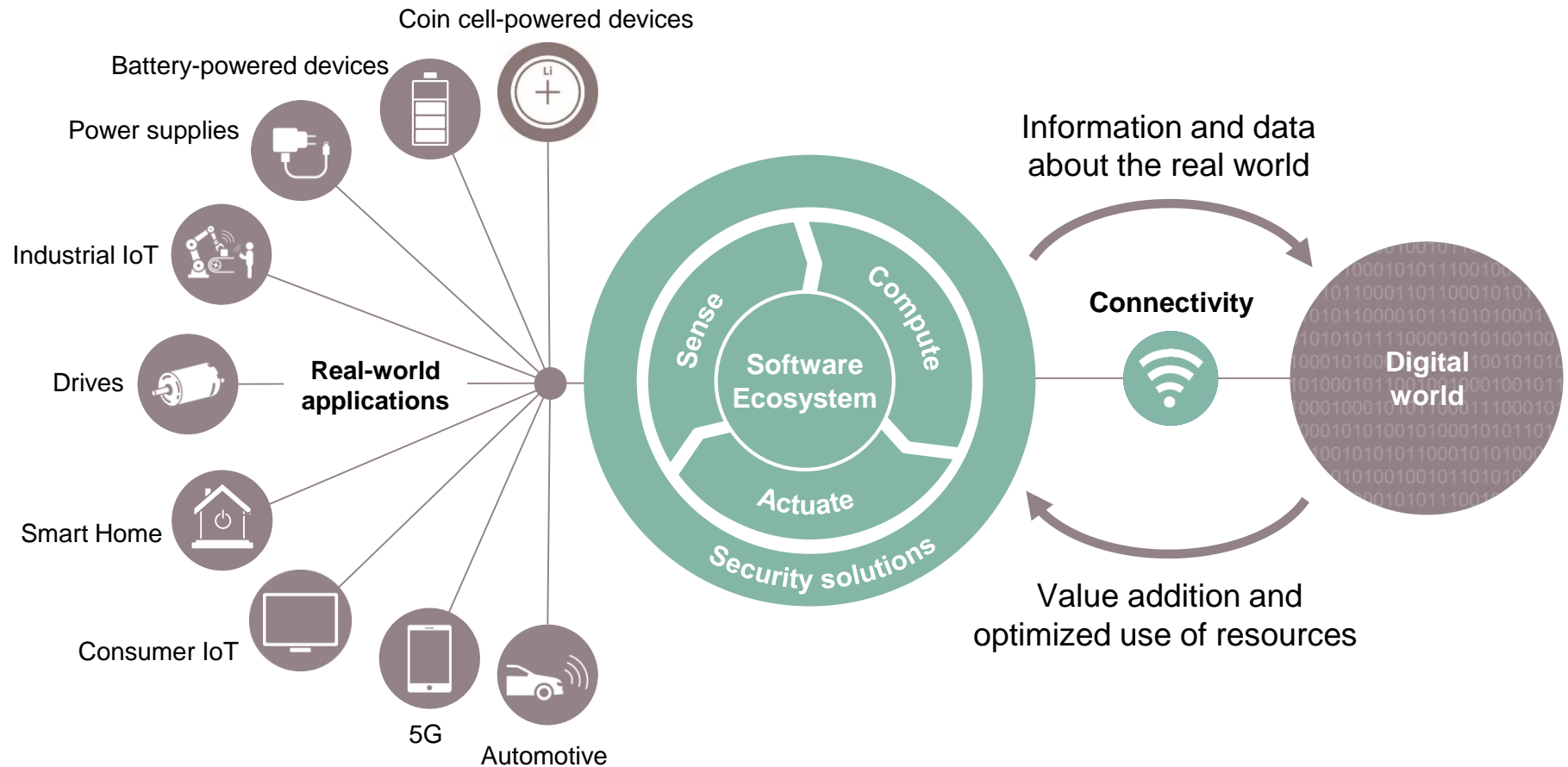


- › combined FY19 revenue of approx. €10bn
- › top 10 in the semiconductor industry
- › leading player in automotive, systems for power management and drives, sensor systems, connected secure systems, wireless combos, differentiated memories



- › expected revenue synergy potential of > €1.5bn p.a. from FY28 onwards
- › expected cost synergies of €180m p.a. gradually ramping up over approximately three years after closing
- › expected to be accretive to adjusted EPS in FY21
- › improved target operating model
 - 9%+ revenue growth
 - 19% Segment Result margin
 - 13% investment-to-sales

Infineon offers a unique portfolio that links the real and the digital world



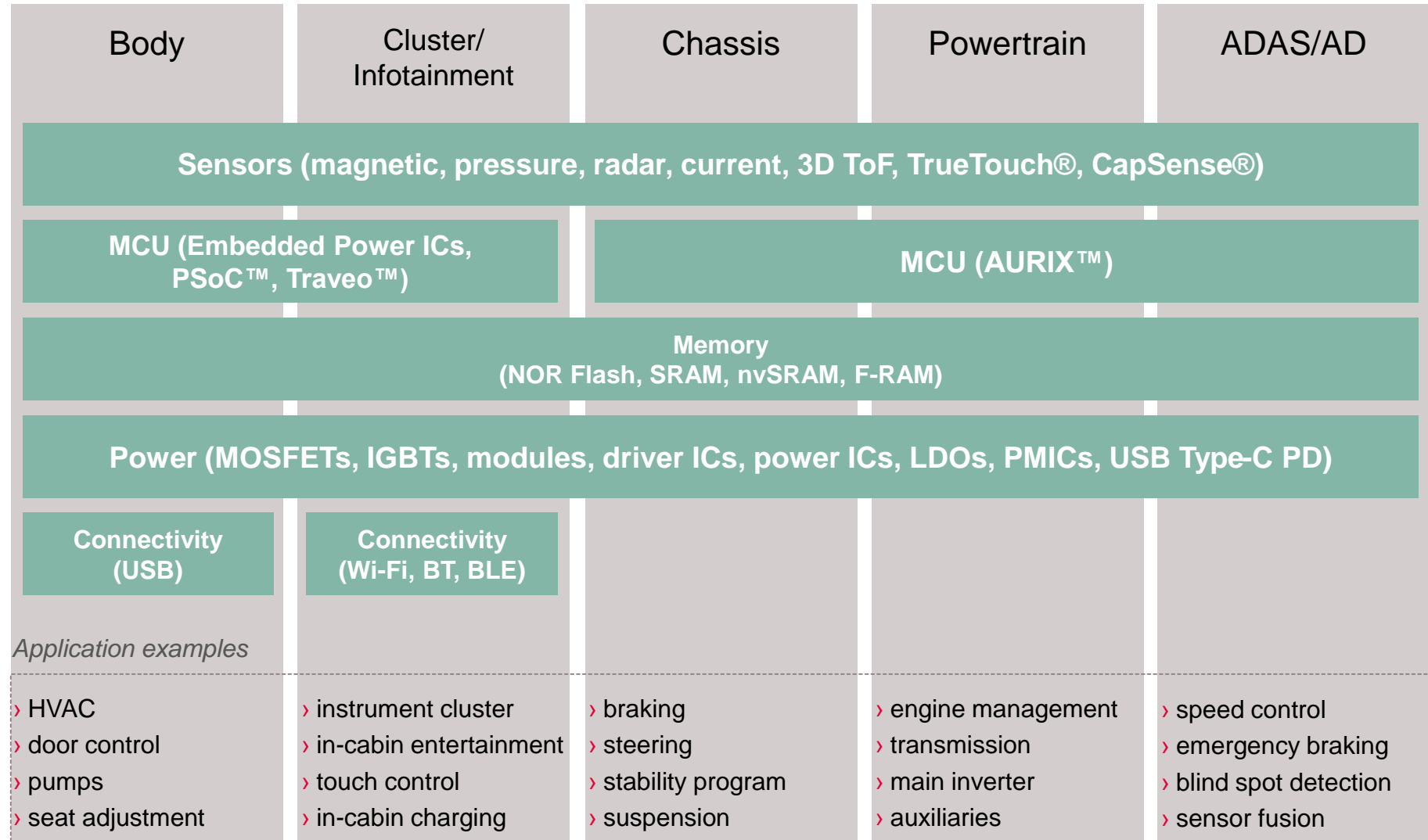
Sense: sensors

Compute: microcontrollers,
memories

Actuate: power semiconductors

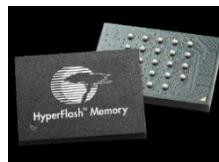
Connectivity: Wi-Fi, Bluetooth, USB

Infineon has industry's broadest product portfolio covering entire range of auto applications



NOR Flash benefits from growing use of flash-less processing units (MCUs, GPUs, FPGAs, SoCs)

- › Advanced process nodes (28 nm and below) no longer offer embedded NOR Flash economically → trends towards off-chip memory
- › Infineon's high-density NOR Flash is used as
 - › boot-up memory and
 - › instant-on program memory
- › Leader in high-density products (16 Mb – 4 Gb)
- › Semper™ Flash best positioned in functionally safety (ISO 26262 ASIL-B) and security for ADAS/AD
- › focusing on safety-critical applications in automotive, industrial, and communications



Automotive

- › ADAS/AD
- › instrument clusters
- › navigation systems
- › SOTA updates

Industrial

- › programmable logic controller
- › GPS board

ICT

- › 5G infrastructure (radio heads)
- › gateways
- › scanner, printer

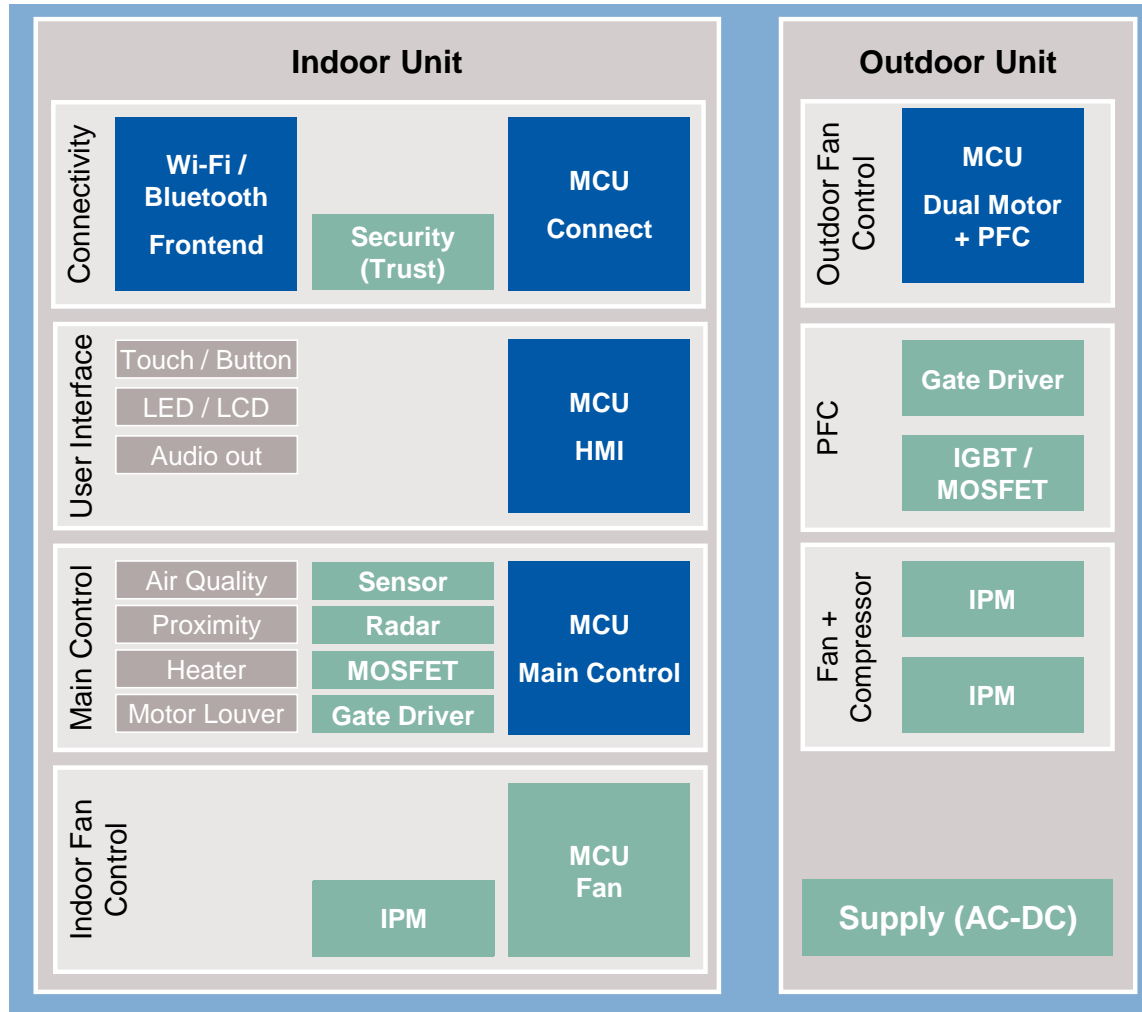
Consumer

- › ear pods
- › digital camera

With the combined portfolio Infineon can offer full system solutions



Example: air-conditioning



What makes system solution attractive to customers?

- › **Ease of design**
⇒ combined portfolio covers all relevant system components
- › **Superior quality**
⇒ integrated solution ensures MCU, power stage and peripherals work perfectly together
- › **Faster time-to-market**
⇒ no additional integration or software development costs

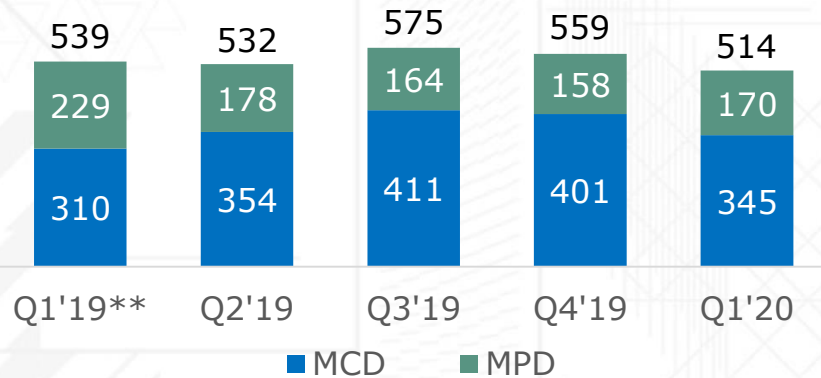
Infineon heritage

Cypress heritage

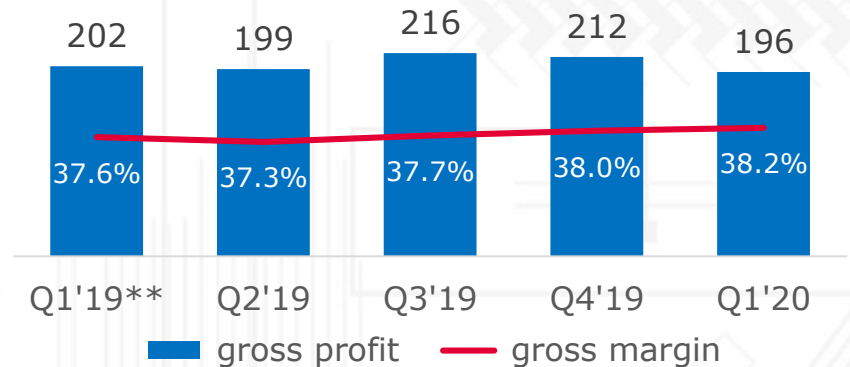
Cypress financial performance*

numbers may not add up due to rounding

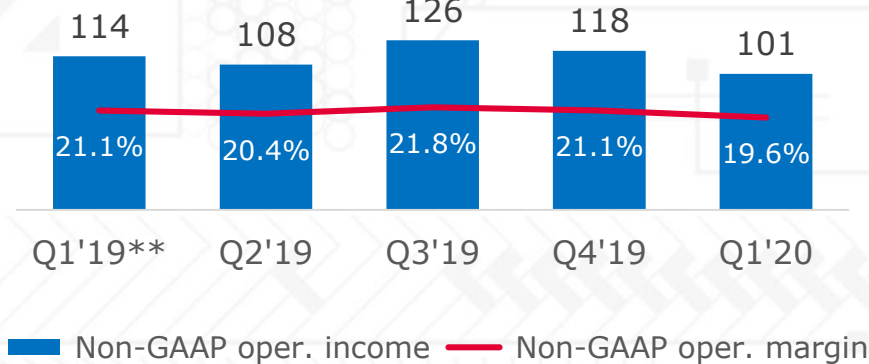
Revenue development [\$ m]



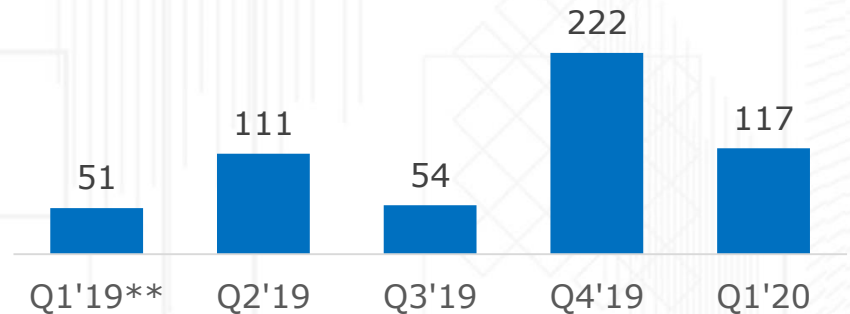
Gross profit [\$ m], gross margin



Non-GAAP operating income [\$ m], Non-GAAP operating margin



Free cash flow*** [\$ m]

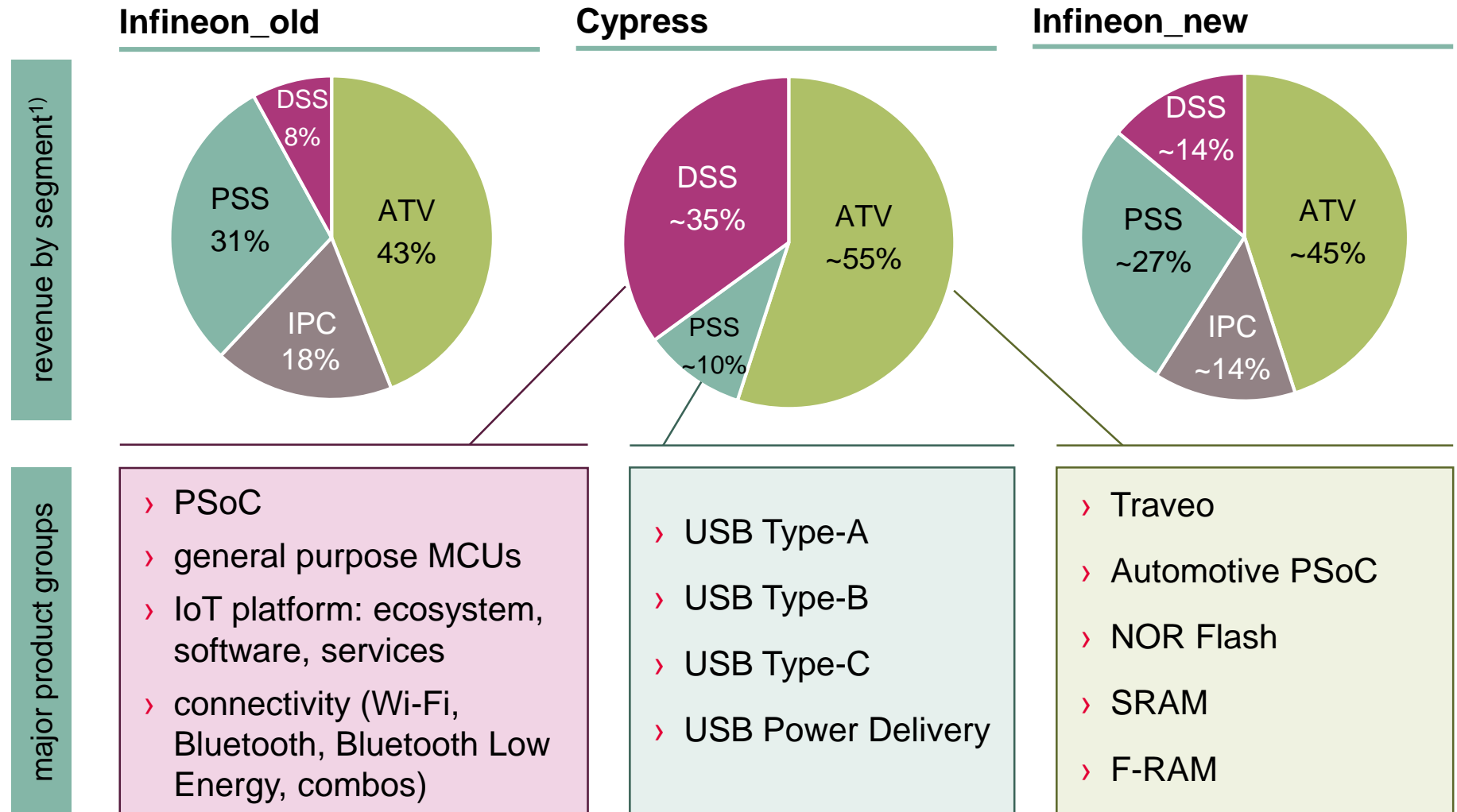


* Unaudited financials based on US-GAAP; for further details see www.infineon.com/ir/cypress.

** Q1'19 results include the NAND Flash business which was divested in Q2'19. Revenues of the NAND Flash business in Q1'19 were included in MPD.

*** Free cash flow is calculated as net cash provided by (used in) operating activities, less net of acquisitions and sales of property, plant and equipment.

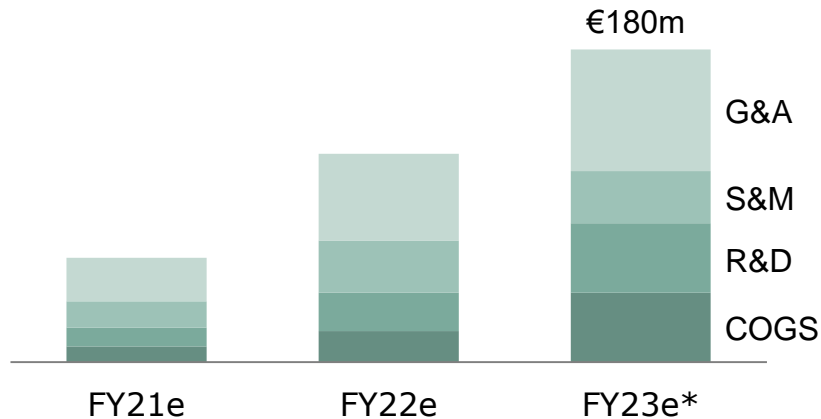
Allocation of Cypress revenue leads to a more balanced portfolio



1) in the 12-month period ended March 2020

Short-term reaping of cost synergies, long-term value creation of revenue synergies

Planned ramp-up of cost synergies



COGS

- › Procurement for materials and manufacturing services

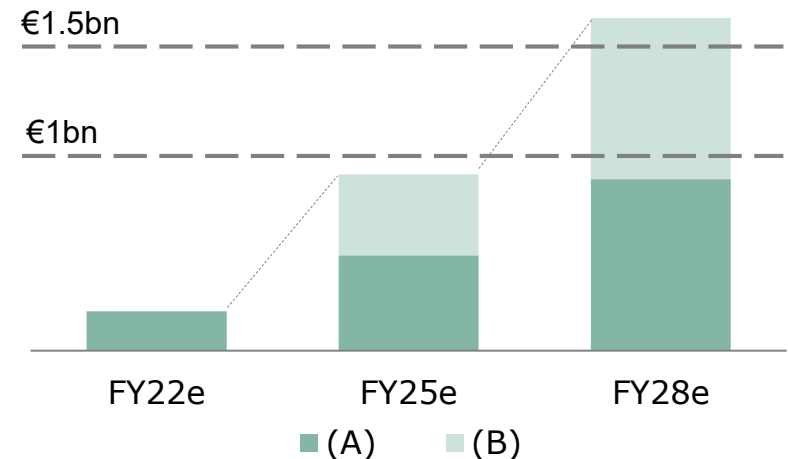
OpEx

- › R&D: Optimize portfolio, reduce overhead
- › S&M: Efficiency gains in account coverage
- › G&A: Optimize corporate service providers

Expected integration and restructuring costs equivalent to ~1x cost synergies one-off over time

* Expected cost synergies of €180m p.a. gradually ramping up over approximately three years after closing. Ramp progression adjusted for later closing and COVID-19 implications.

Planned ramp-up of revenue synergies






(A) Near-term revenue synergy ramp up

- › Improved customer access and cross-selling
- › Optimize Cypress digital marketing potential to address revenue opportunities and grow customer numbers

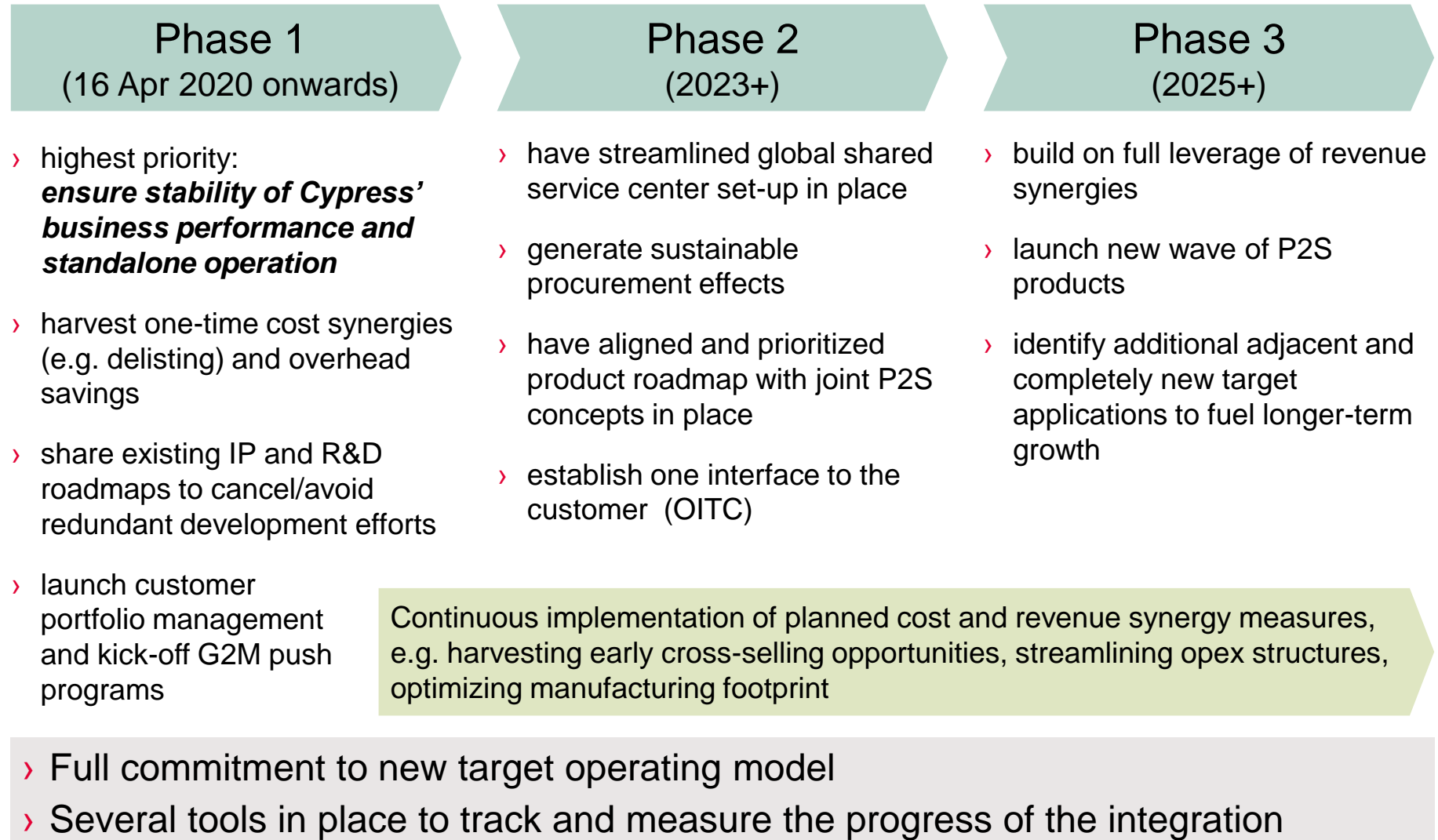
(B) P2S for long-term revenue synergy ramp up

- › Sensor systems and connectivity in IoT applications
- › wireless connectivity in automation equipment
- › Security-hardened controllers and connectivity
- › systems for power management and drives
- › differentiated memories in mission critical applications

Further improvement of through-cycle target operating model

Target Operating Model		Infineon financial performance to approach targets as integration progresses
Revenue growth		9%+ (up from “9%”)
Segment Result margin		19% (up from “17%”)
Investment-to-sales		13% (down from “15%”)

Well-defined roadmap how to capture the value of the deal (delayed by unpredictable COVID-19 pandemic)



After successfully completing the equity part of the refinancing, focus will now shift to the debt part

2019

- › Arranging and syndication of acquisition facility ✓
- › Initial equity de-risking in two steps:
 - › €1.5bn via ABB ✓
 - › €1.2bn via dual-tranche hybrid bond ✓

2020

- › Drawdown of acquisition facility and usage of raised funds ✓
- › Investment grade rating of BBB- by Standard & Poor's ✓
- › Completion of equity part via €1.0bn ABB ✓

NEXT

- › Refinancing of remaining acquisition facility with maturities from March 2022 to June 2024 through debt capital markets
- › Liquidity: keeping gross cash target of €1bn plus at least 10% of combined revenue
- › Deleveraging: return to target level $\leq 2x$ gross debt / EBITDA over mid-term

Infineon with moderate financial leverage post Cypress closing



simplified overview; numbers may not add up due to rounding

Pre closing

Infineon per 31 Mar 2020 [EUR bn]

gross cash	4.6	gross debt ¹⁾	1.5
net cash	3.1		

Cypress per 29 Mar 2020 [EUR²⁾ bn]

gross cash	0.8	gross debt reported	1.0
		gross debt effective ³⁾	1.3
		net debt effective	0.5

Acquisition financing

Sources [EUR bn]

Acquisition financing facilities	
– bridge	3.9
– term loan	3.0
Infineon gross cash	2.5
total	9.4

Uses [EUR²⁾ bn]

Cypress shares ⁴⁾	8.1
Cypress gross debt effective	1.3
total	9.4

Post closing

Assumpt.: all pre-existing Cypress debt paid off

Infineon per 31 Mar 2020 [EUR bn]

gross cash	2.9	gross debt	8.5
		net debt	5.6

Post ABB May 2020 (€1bn)

ABB proceeds used to pay off debt

Infineon per 31 Mar 2020⁷⁾ [EUR bn]

gross cash	2.9	gross debt	7.5
		net debt	4.6

- › **net debt/EBITDA:** 2.0x
- › **gross debt/EBITDA:** 3.3x

- 1) does not include hybrid bond; considered as equity under IFRS
- 2) based on an exchange rate of \$1.0977 for €1.00
- 3) assuming conversion values of Cypress convertible instruments
- 4) excluding stock options and accelerated vested restricted stock units (RSU)
- 5) Cypress FCF calculated – in alignment to the FCF definition of Infineon – as total of net cash provided by operating activities and net cash used in investing activities
- 6) figure contains Infineon financial information prepared in accordance with IFRS as well as Cypress financial information prepared according to US-GAAP. Neither US-GAAP / IFRS conversion has been performed, nor purchase price allocation effects have been considered
- 7) adjusted for the effects of the accelerated bookbuilding

Aggregated unaudited combined EBITDA,
12-month period ended March 2020⁶⁾: **€2.3bn**

- › On an aggregated unaudited basis, Infineon and Cypress together generated FCF⁵⁾ of €0.9bn in the 12-month period ended March 2020⁶⁾

Outlook for Q3 FY20 and FY20 including Cypress

	Outlook Q3 FY20*	Outlook FY20*
Revenue	€1.9bn to €2.3bn	~ €8.4bn +/- 5%
Segment Result margin	At the mid-point of the revenue guidance: positive mid-single digit percentage	At the mid-point of the revenue guidance: ~12%
Investments in FY20		€1.2bn – €1.3bn**
D&A in FY20		~€1.0bn***

* Based on an assumed average exchange rate of \$1.10 for €1.00 (previously \$1.13 for €1.00).

** Formerly ~€1.3bn for Infineon standalone.

*** Outlook does not yet include D&A on tangible and intangible assets from purchase price allocation of Cypress acquisition. On the other hand, outlook includes D&A on tangible and intangible assets from purchase price allocation of about €60m, primarily to International Rectifier.

Tight customer relationships, based on system know-how and application understanding



ATV	IPC	PSS	DSS
EMS partners	Distribution partners		



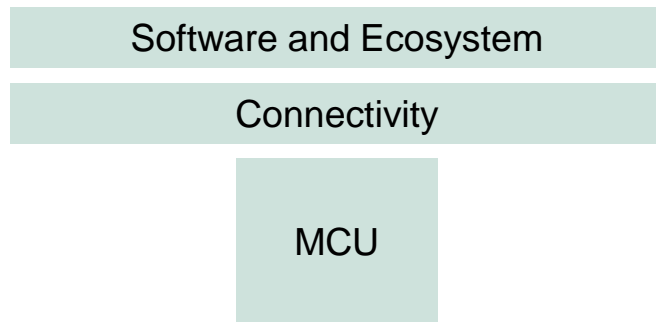
Digital Security Solutions



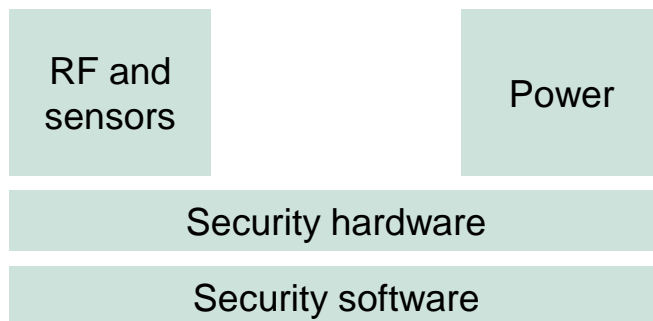
In IoT, Cypress and Infineon portfolio complement perfectly to offer best-in-class solutions

Past: standalone IoT offerings from Infineon and Cypress

Cypress standalone offering:

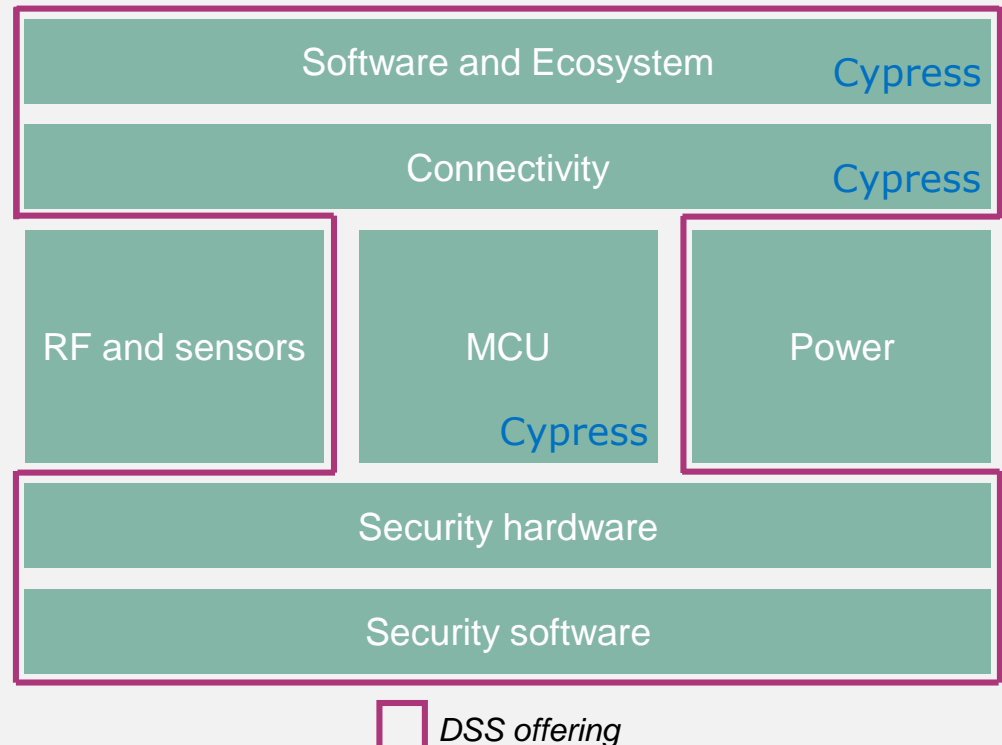


Infineon standalone offering:

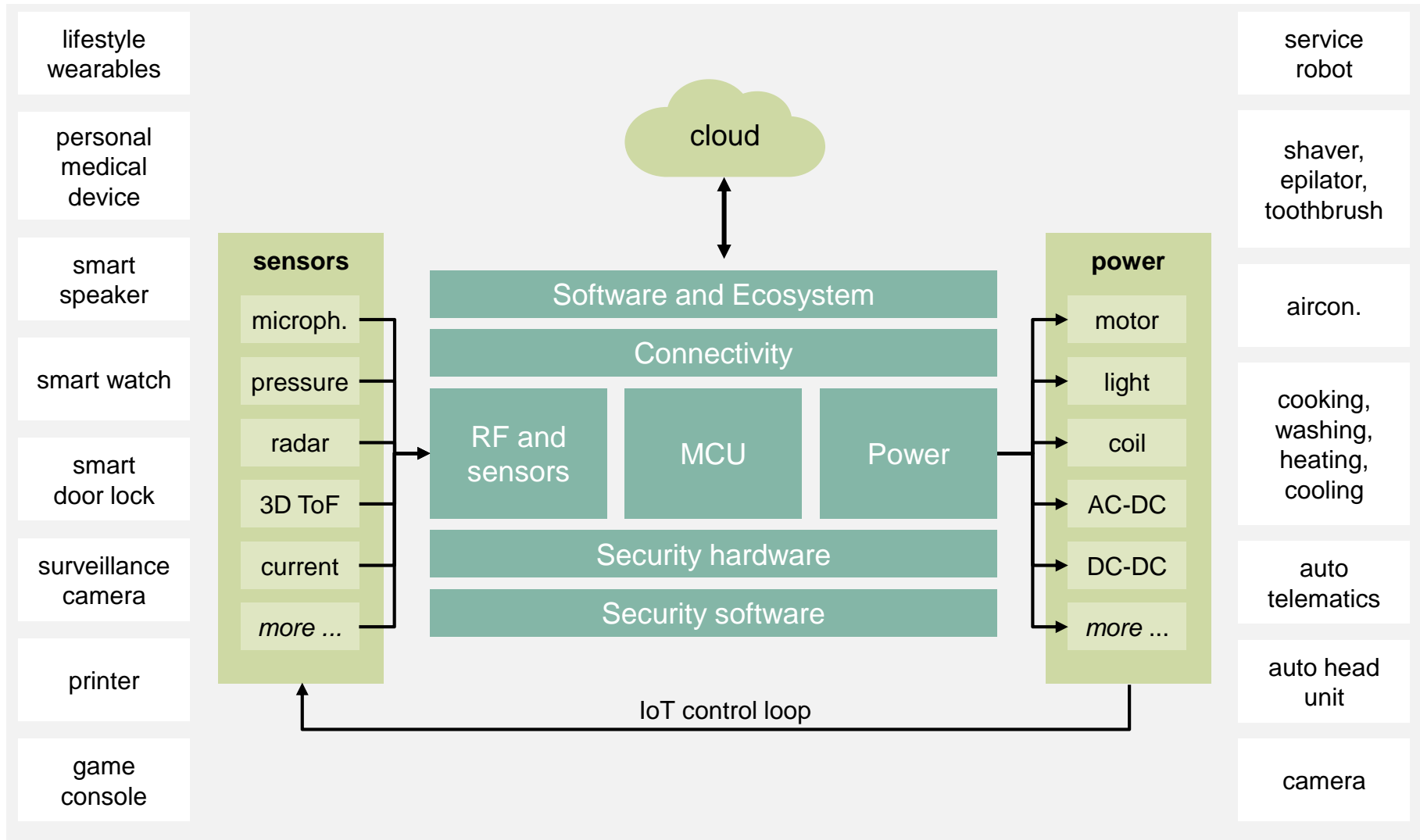


Now: combined IoT offerings going forward

Best-in-class solutions - extending Infineon's scope of applications and markets and attracting new customers with new applications

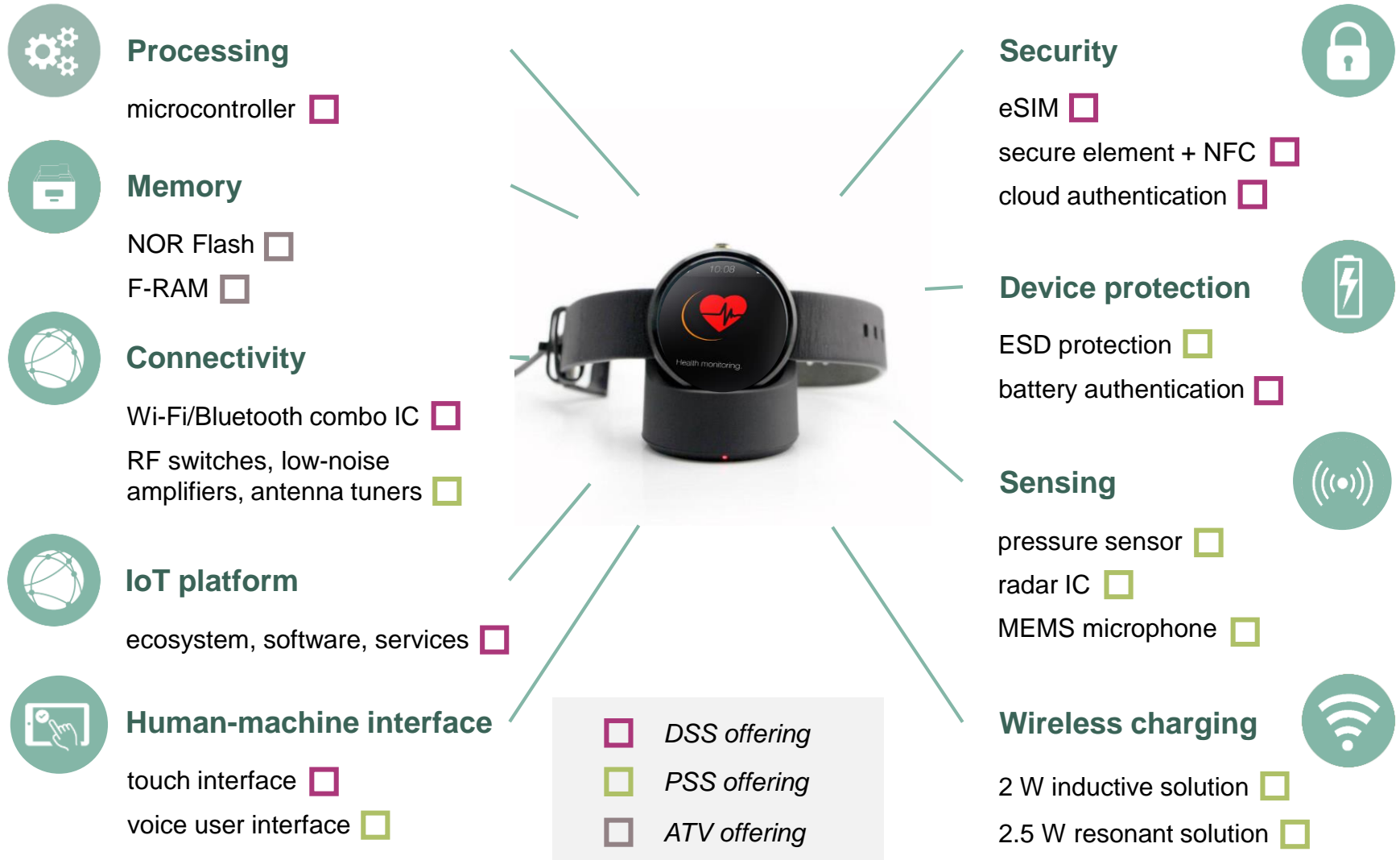


Infineon now offers the entire system for IoT - unlocking new markets and applications



Infineon's system solutions are based on cross-divisional product offerings to max. BoM content

Example: smart watch



DSS has a strong, comprehensive offering with high differentiations



Microcontroller

- › 15+ years of investment in PSoC portfolio with > 2bn MCUs shipped
- › major advantages of programmability and low power consumption
- › integrated security as a key feature, especially for IoT



Connectivity

- › excellent market reputation; 1bn+ wireless nodes shipped
- › proven interoperability between Wi-Fi and BT/BLE as well as monolithic integration into MCUs
- › a leader in combos and software stack ⇒ key for IoT applications



Security

- › leading security market player; unrivaled in security and contactless competence
- › full solution offered with software – making security easy-to-implement, especially for IoT devices



Software

- › industry-leading software and toolbox: WICED, MODUS Toolbox
- › software as a key differentiator and a major enabler for fast and easy implementation of MCU, connectivity and security solutions in IoT devices



Ecosystem

- › established developer community for hardware and software
- › fast, proven technical support infrastructure



Automotive

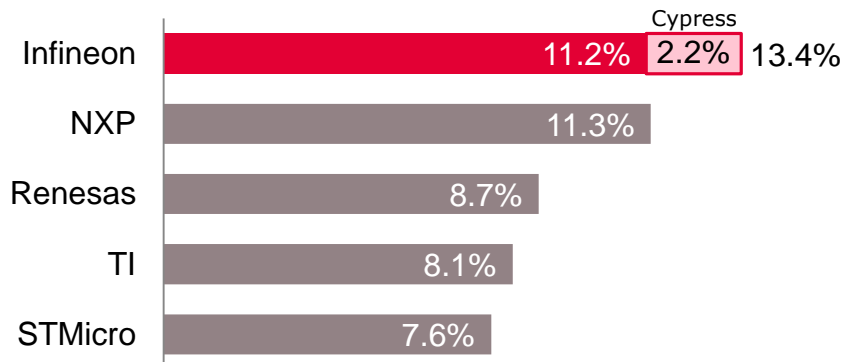


Infineon and Cypress create the new number 1 in the automotive semiconductor universe



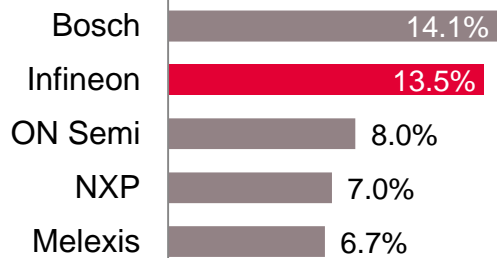
Automotive semiconductors

2019 total market: \$37.2bn

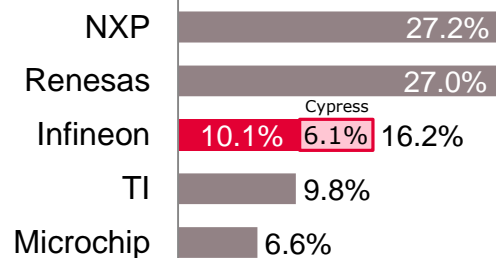


- › Cypress contributed 2.2%-points to the combined automotive semiconductor market share of 13.4%
- › Cypress contributed 6.1%-points to the combined automotive microcontroller market share of 16.2%
- › Infineon is the #2 automotive memory supplier with a market share of 13.2% (total contribution by Cypress, mainly NOR Flash)

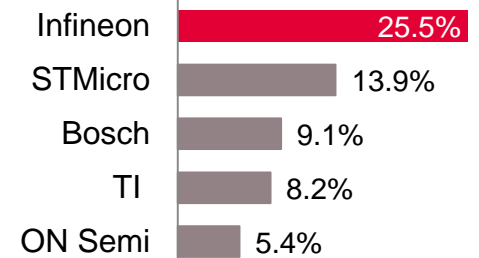
Sensors



Microcontrollers



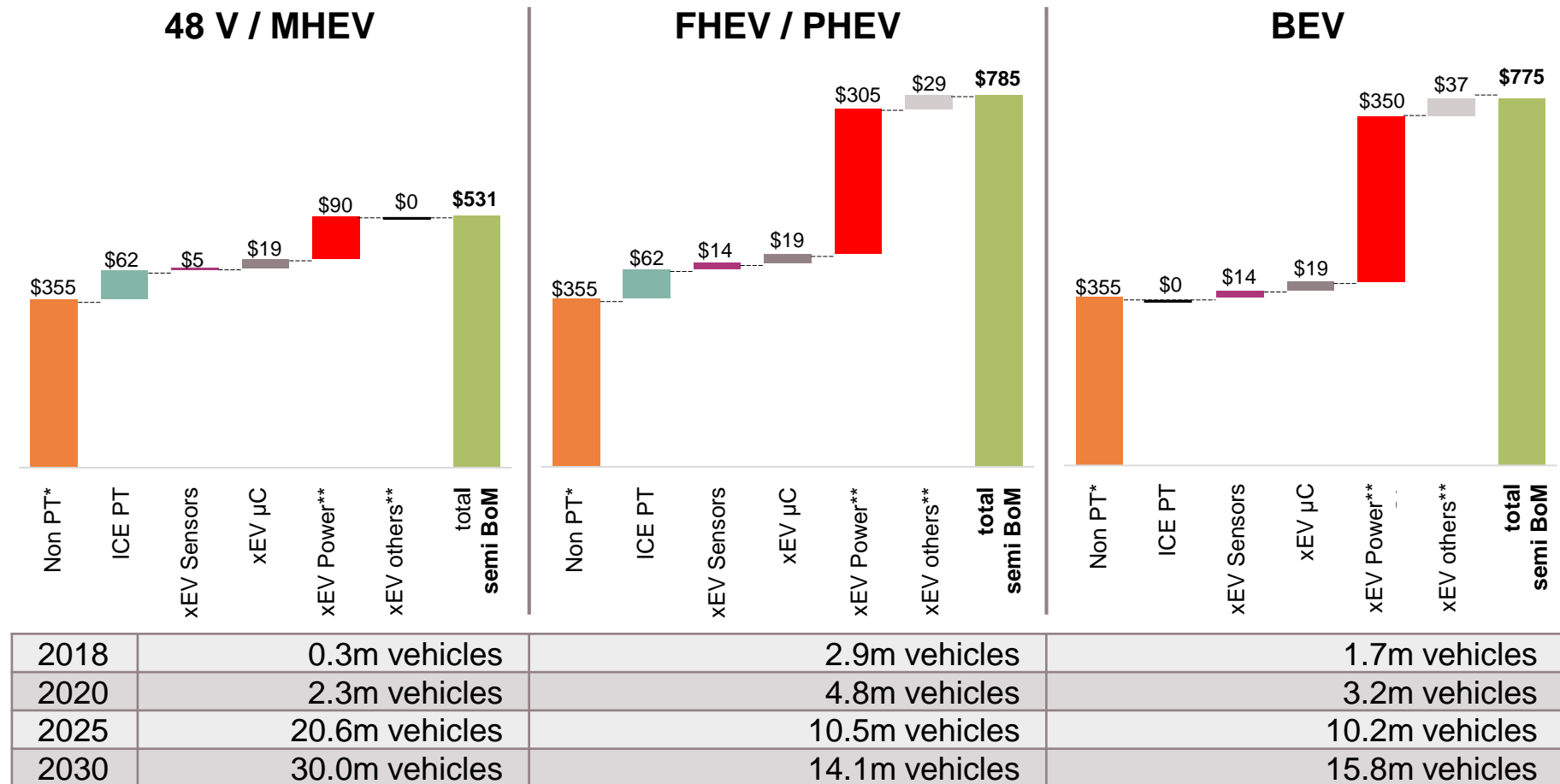
Power



Source: Strategy Analytics, "Automotive Semiconductor Vendor Market Shares v2", May 2020. The acquisition of Cypress by Infineon closed on 16 April 2020. The market shares for 2019 shown here are the combined market shares of Infineon and Cypress based on their individual figures.

The incremental demand of power semiconductors is a significant opportunity

2019 average xEV semiconductor content by degree of electrification



Source: Infineon; IHS Markit, Automotive Group, "Alternative propulsion forecast", September 2019; Strategy Analytics, "Automotive Semiconductor Content", August 2019.

* Non PT (non powertrain): average semiconductor content in Body, Chassis, Safety & Infotainment application segments.

** "power" includes linear and ASIC; "others" include opto, small signal discrete, memory

ADAS/AD semi growth driven by radar and camera sensor modules over the next 5 years



Average semiconductor content per car by level of automation at the given years

NCAP 5 Star/AD L2

L2 vehicles in 2020: ~6m

AD L2+

L2+ in 2022: ~1m

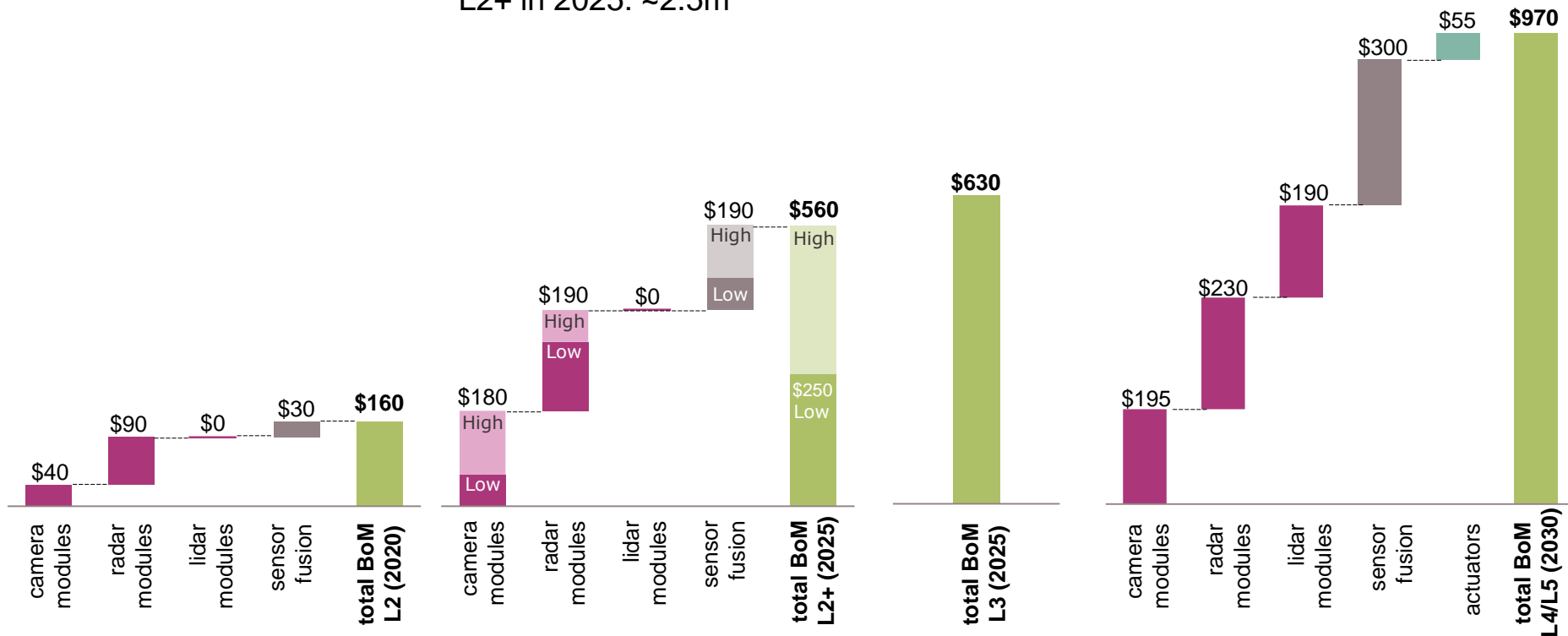
L2+ in 2025: ~2.5m

AD L3

L3 in 2025: ~1.5m

AD L4/L5

L4/L5 vehicles in 2030: ~4m



Source: Strategy Analytics; Infineon.

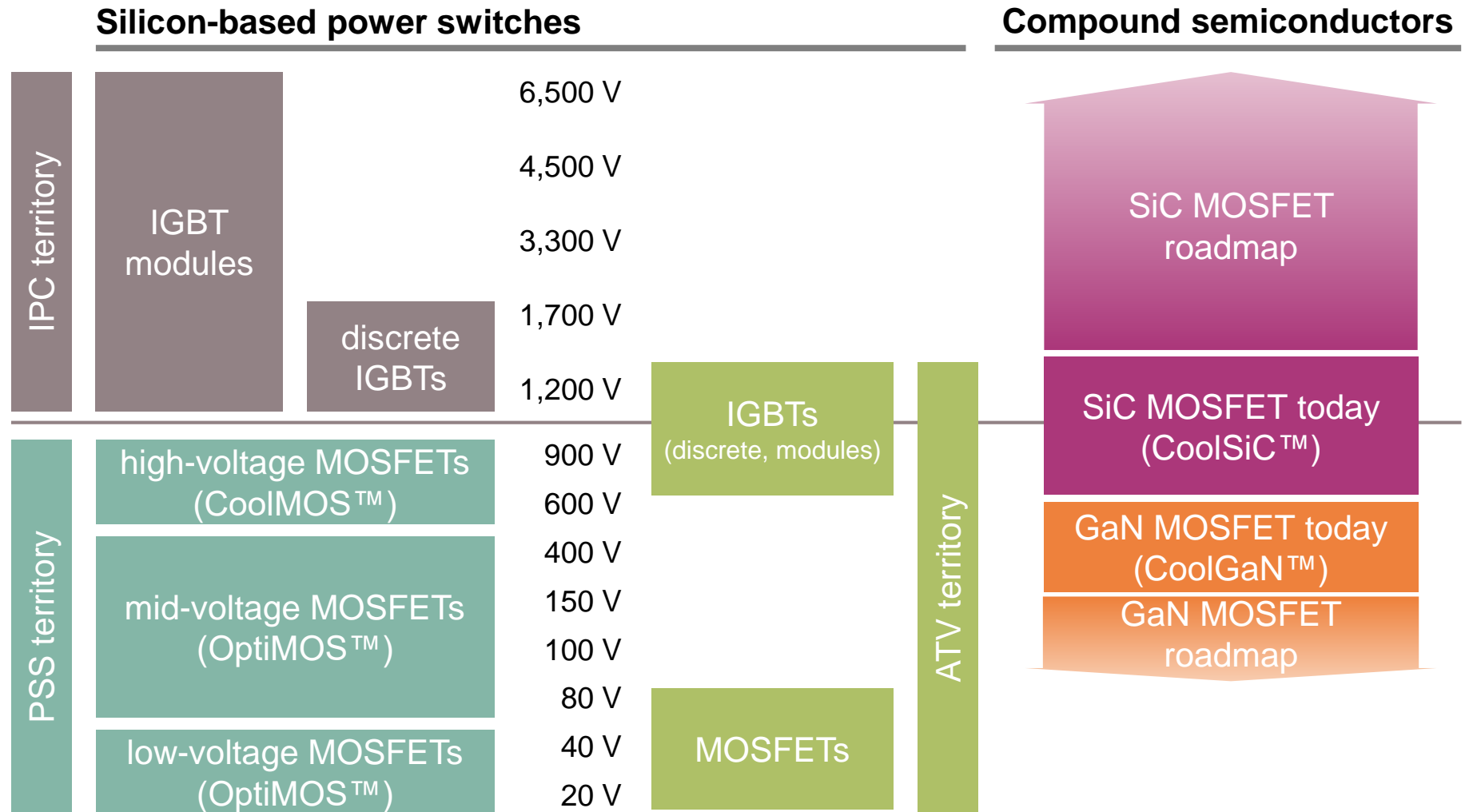
BoM contains all type of semiconductors (e.g. radar modules include μ C); sensor fusion does not include memory. BoM are projected figures for the respective time frame.

Sense Interp. & dec. Act



Infineon's power strategy

Infineon's discrete power portfolio* is basically separated by voltage classes



* excluding drivers and control ICs

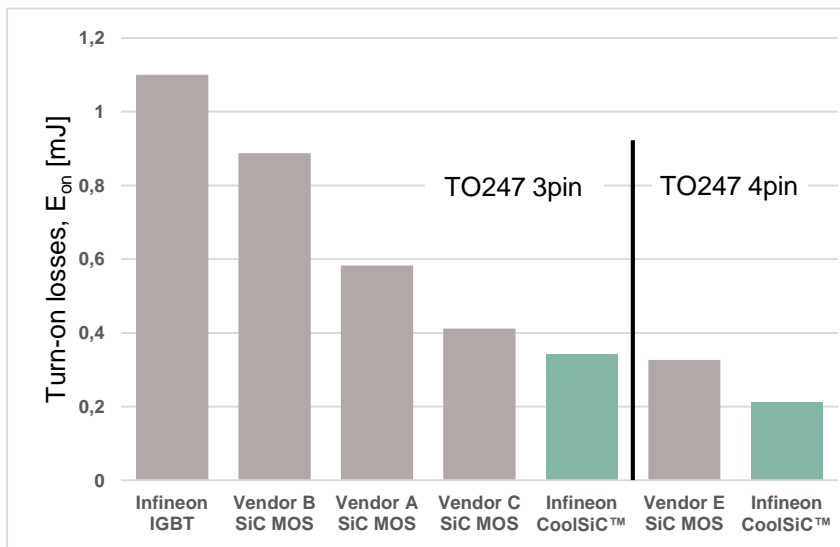
Second generation (2nd Gen.) CoolSiC™ Trench MOSFET will increase the addressable market

1st Gen. CoolSiC™ Trench MOSFET
is the leading technology today



2nd Gen. CoolSiC™ Trench MOSFET
is in advanced development phase

1st Gen. with lowest losses



Source: Infineon, datasheets on supplier web pages, September 2019.

1st Gen. CoolSiC™ Trench MOSFET
has set the industry benchmark

2nd Gen. will expand the lead

- › Enhanced power handling capability by 25% – 30%
- › Enhanced safe operating area without compromising quality
- › Enabling SiC in further high volume applications

2nd Gen. CoolSiC™ Trench MOSFET
will significantly enlarge the market
size for SiC MOSFETs

Status of implementation of Cold Split technology

Process tools	Clean room	Process flow
<ul style="list-style-type: none"> › Design and production of semi-automated process tool park completed in Dresden 	<ul style="list-style-type: none"> › Clean room ready for manufacturing by end of calendar year 2020 	<ul style="list-style-type: none"> › Integration of individual process steps into complete work flow

1/3 of the industrialization journey accomplished

Wafer splitting by 2022	Boule splitting by 2023
<ul style="list-style-type: none"> › Wafer for splitting are already available › Increases # of wafers up to a factor of 2 	<ul style="list-style-type: none"> › Boules start to become available › Increases # of wafers by a factor of 2.0 in a first step, with potential for a factor of 2.6

Combining boule splitting and wafer splitting will make the most efficient process

Infineon is ready to support and shape the growing SiC device market



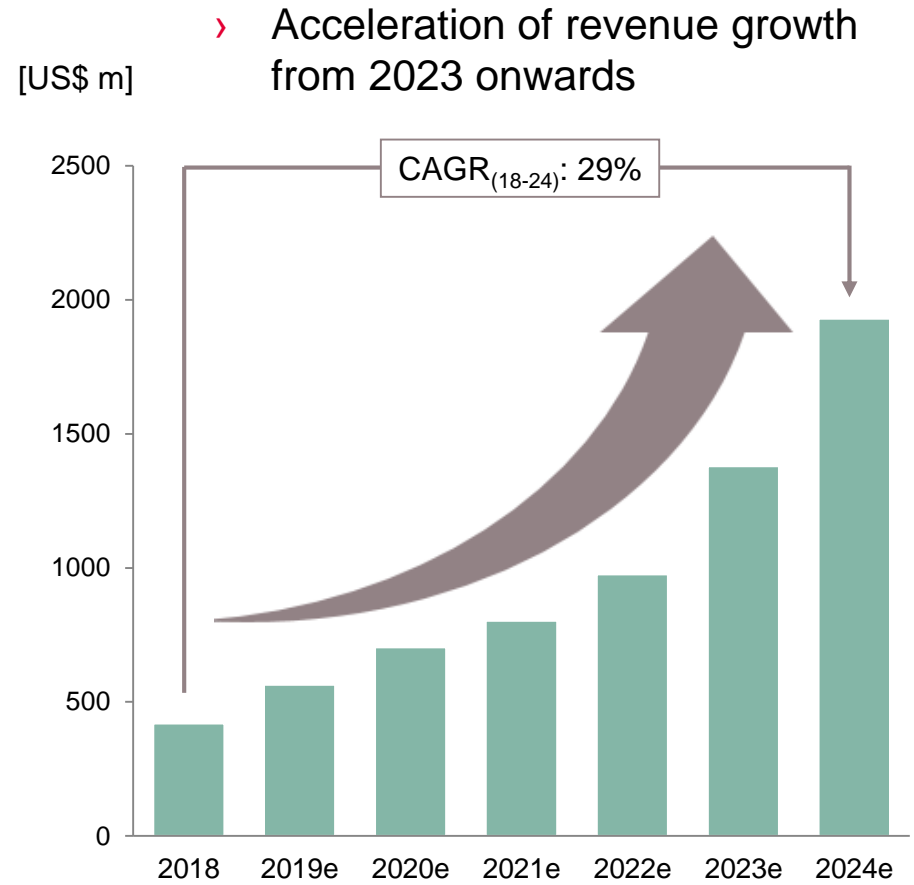
Today

- › Leading Infineon technology with 1st Gen. CoolSiC™ Trench MOSFET
- › Already broad, fast growing portfolio
- › System expertise and customer access

Strategic projects to support growth

- › 2nd Gen. CoolSiC™ Trench MOSFET
- › Cold Split: wafer and boule
- › Manufacturing lines already capable of processing 200 mm diameter

SiC device market revenue



Source: Yole, " Power SiC 2019: Materials, Devices and Applications 2019", July 2019.



Industrial Power Control

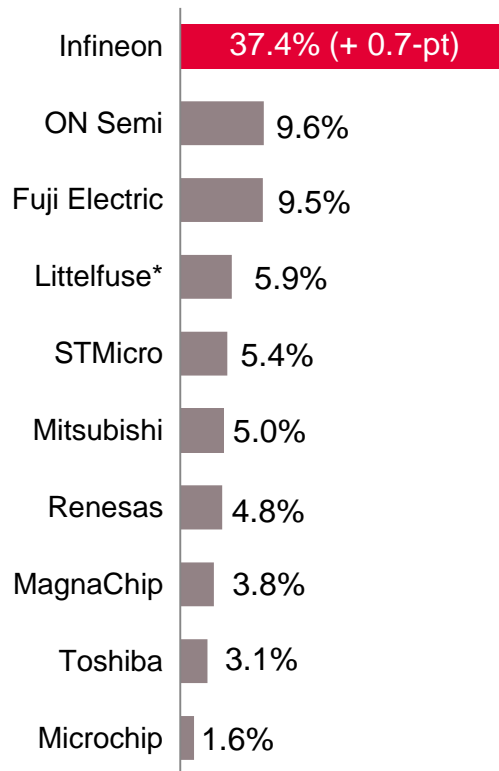


Clear leader in discrete IGBTs and IGBT modules; IPMs strengthened again



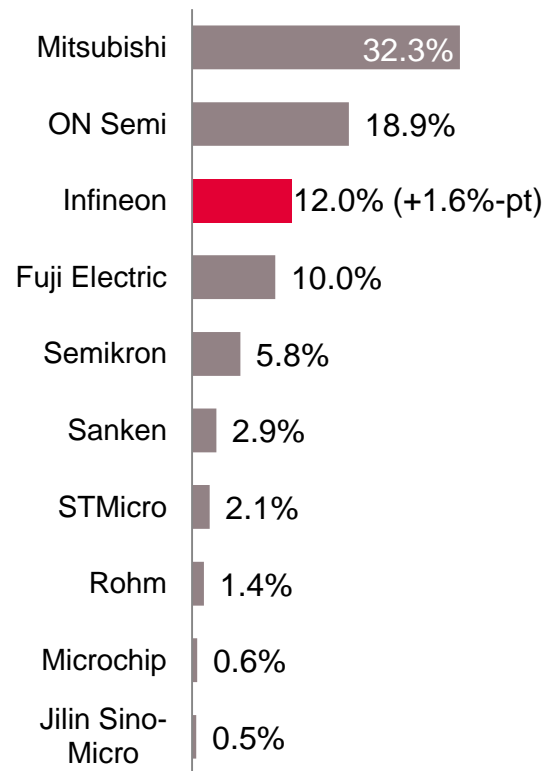
Discrete IGBTs

2018 total market: \$1.31bn



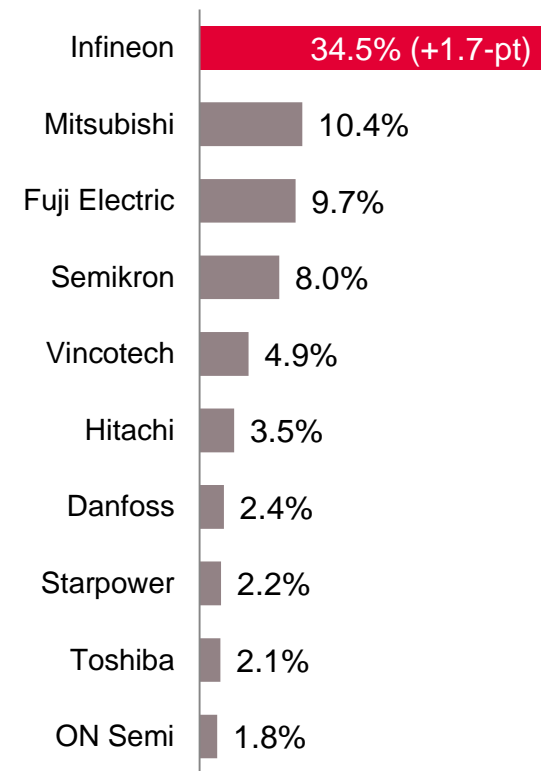
IPMs

2018 total market: \$1.68bn



IGBT modules**

2018 total market: \$3.25bn



* Littelfuse acquired IXYS Corporation in January 2018. Both companies are reported separately in 2017 and combined as Littelfuse in 2018.

** Including standard (non-integrated) IGBT modules and power integrated modules (PIMs) / converter inverter brake (CIB) modules.

Source: Based on or includes research from Omdia, "Power Semiconductor Market Share Database 2018", September 2019.



Power & Sensor Systems – Power

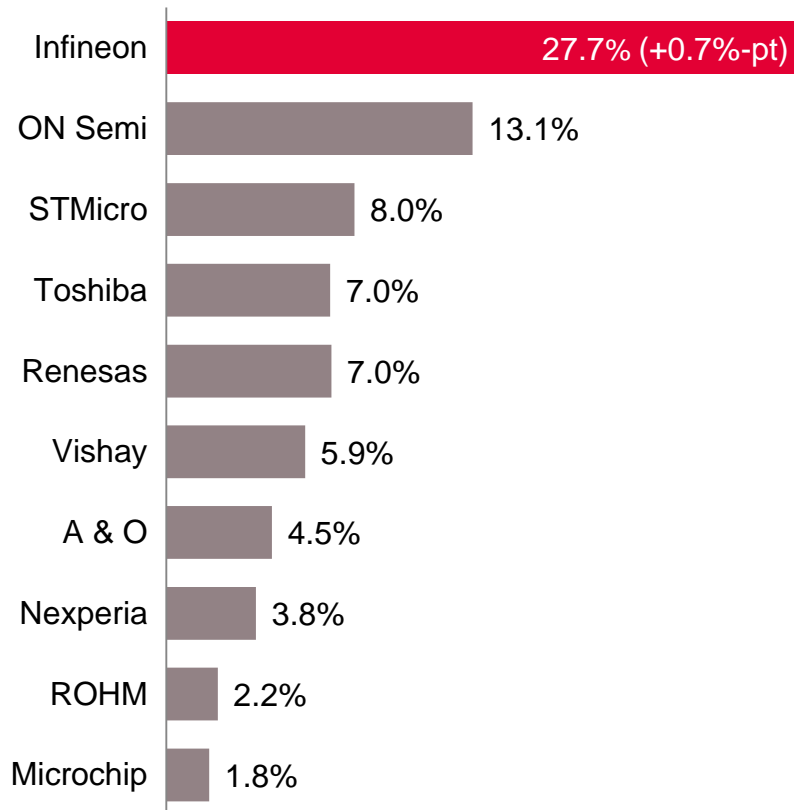


Infineon is the clear leader in MOSFETs; growth potential in power ICs



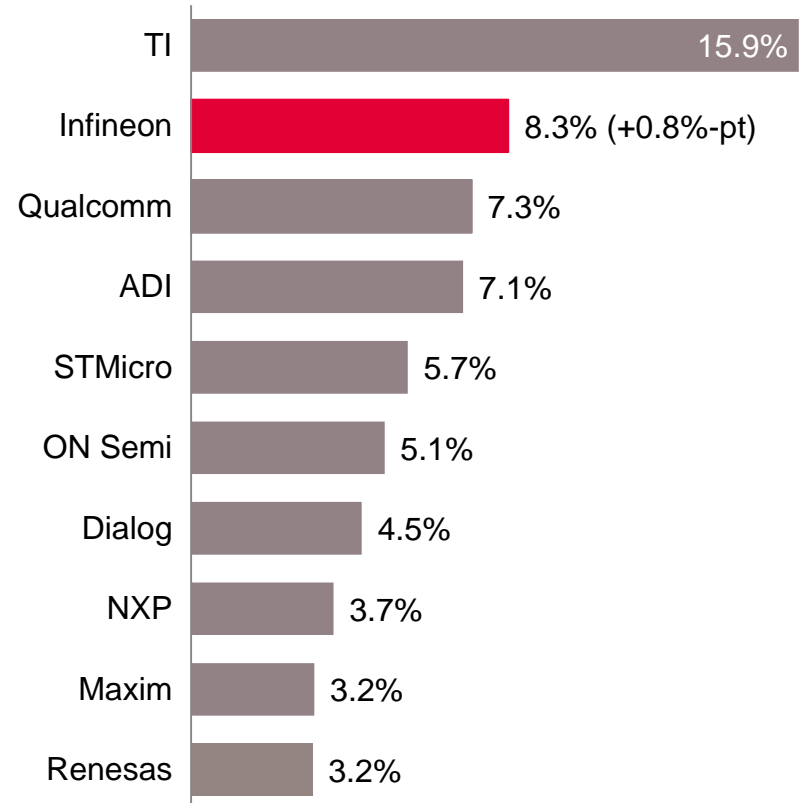
Discrete Power MOSFETs

2018 total market: \$7.58bn



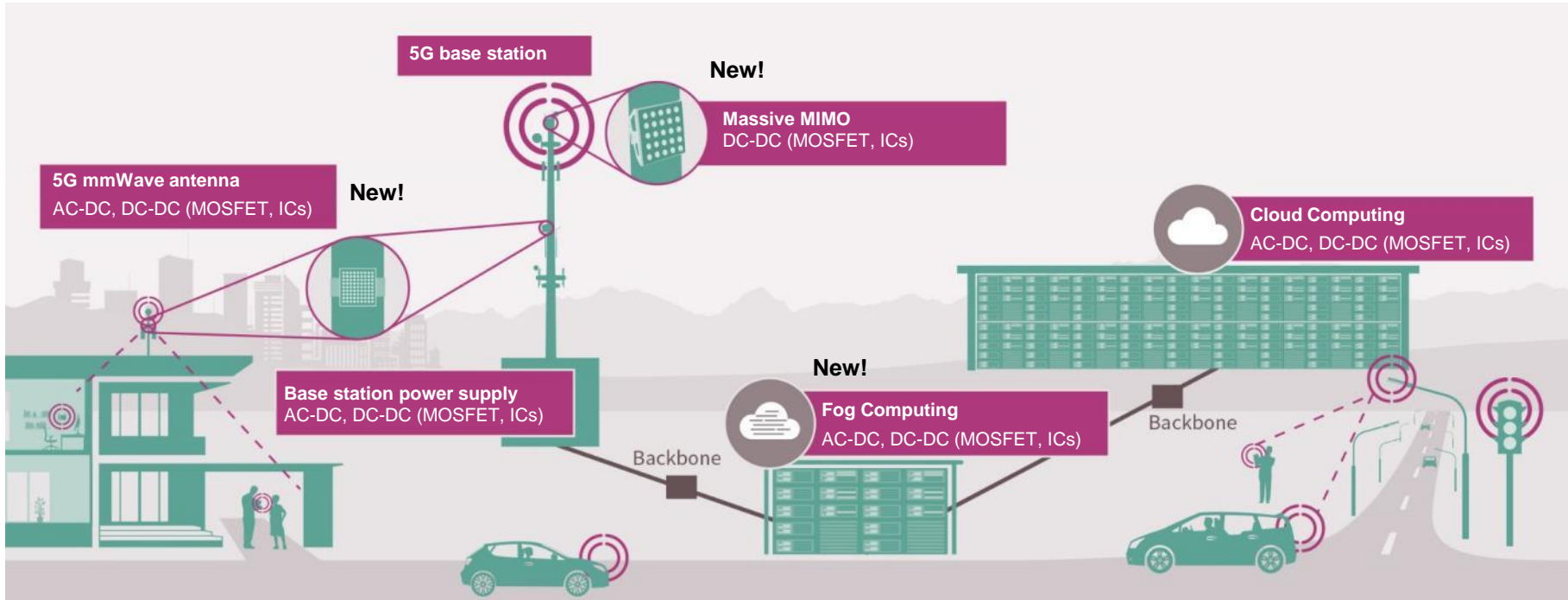
Power ICs

2018 total market: \$25.62bn



Source: Based on or includes research from Omdia, "Power Semiconductor Market Share Database 2018", September 2019.
Discrete Power MOSFET market incl. automotive MOSFETs. Power IC market incl. automotive power ICs.

Transition from 3G/4G to 5G drives demand in power semis for antennas and power supplies



- › driver #1: massive growth of data and computing power
- › driver #2: higher number of base stations due to denser network
- › driver #3: ~4x higher power semiconductor content per radio board:
from ~\$25 for MIMO antenna to ~\$100 for massive MIMO antenna array
- › driver #4: fog computing data center as a completely new market


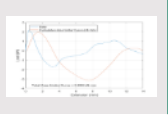


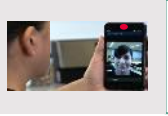


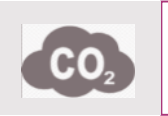
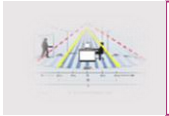





Power & Sensor Systems – RF and Sensing



We focus on MEMS sensors and target to become the leader in 3D sensing and radar



Microphone	Pressure	Environmental	3D radar	3D ToF
 No distortions	 Best-in-class resolution	 6x6mm ² World smallest form factor	 Highest energy efficiency	 Best-in-class resolution
 Receive clear audio signals	 Measure height	 Measure CO ₂	 Biometrics	 3D mapping
 Smart Ears, Smart Feeling, Smart Nose			 Smart Eyes & Sixth Sense	

Key Use Cases – Examples

Voice authentication

Advanced fitness tracking

Smog alarm

Gesture sensing

3D AR gaming

Face recognition & biometric identification

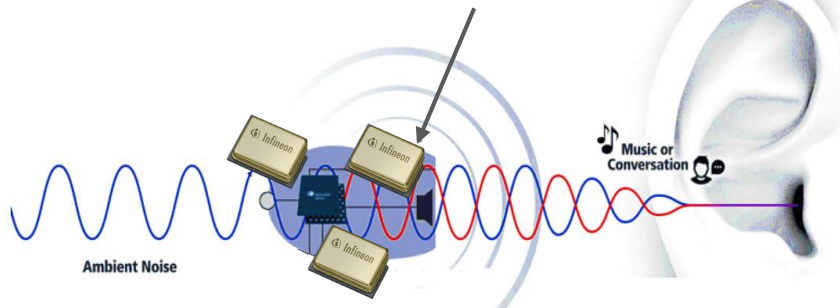
Human Machine Interface

Defining the benchmark for MEMS microphones; Infineon's new sealed dual-membrane technology

- › Unique sealed dual-membrane (SDM) XENSIV™ MEMS microphone design boosts audio pick-up quality
- › Sealing of the capacitive area enables practically noise-free audio signal capturing
- › Inhouse developed packages enable our customers to create outstanding audio experiences:
 - › noise cancellation: in the smallest possible form factor
 - › transparent hearing: clear understanding
 - › binaural recording: create a truly immersive experience



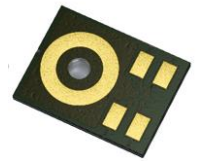
Up to 3 microphones per earbud (6 per set)



XENSIV™ SDM MEMS microphone



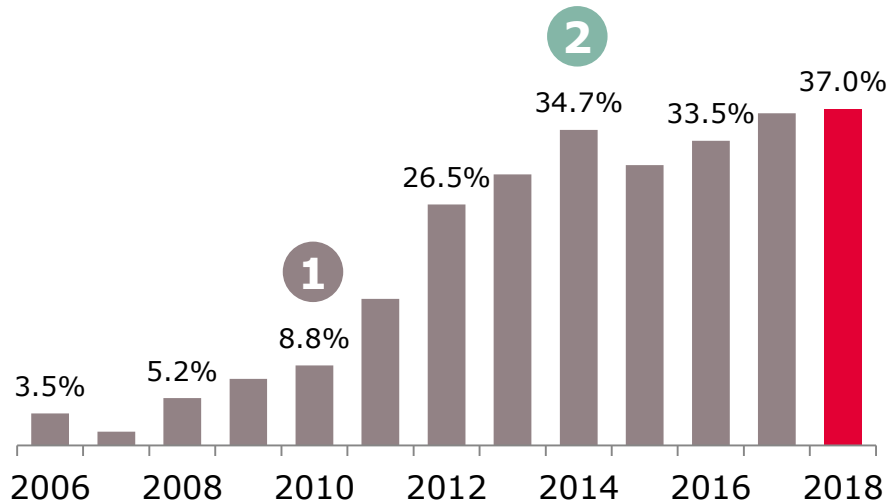
top view



bottom view

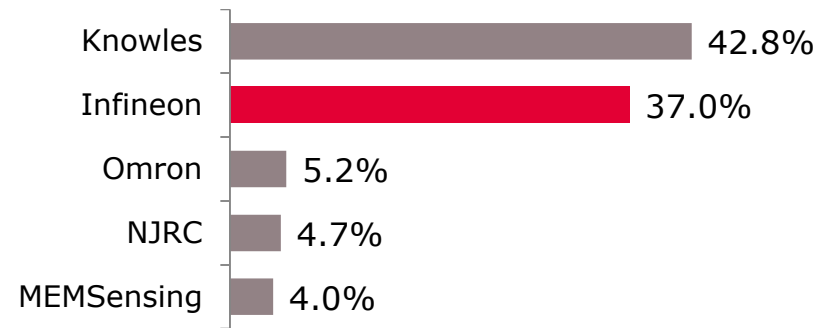
Sweeping success of our XENSIV™ MEMS microphones driven by unparalleled audio characteristics

Infineon's market share development in MEMS microphones



2018 MEMS die market share

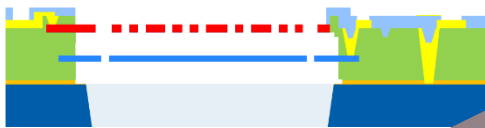
total market: 4.6bn units



Source: Informa Tech, "MEMS Microphone Database 2019", January 2020

Technological progression of Infineon XENSIV™ MEMS microphones

1 Single-back plate



SNR = 58 – 64 dB(A)

2010

2 Dual-back plate



SNR = 63 – 69 dB(A)

2014

3 Sealed dual-membrane



SNR = 68 – 75 dB(A)

2019

Agenda

1

Cypress becomes part of Infineon

2

Digital Security Solutions

3

Automotive

4

Infineon's power strategy

5

Industrial Power Control

6

Power & Sensor Systems

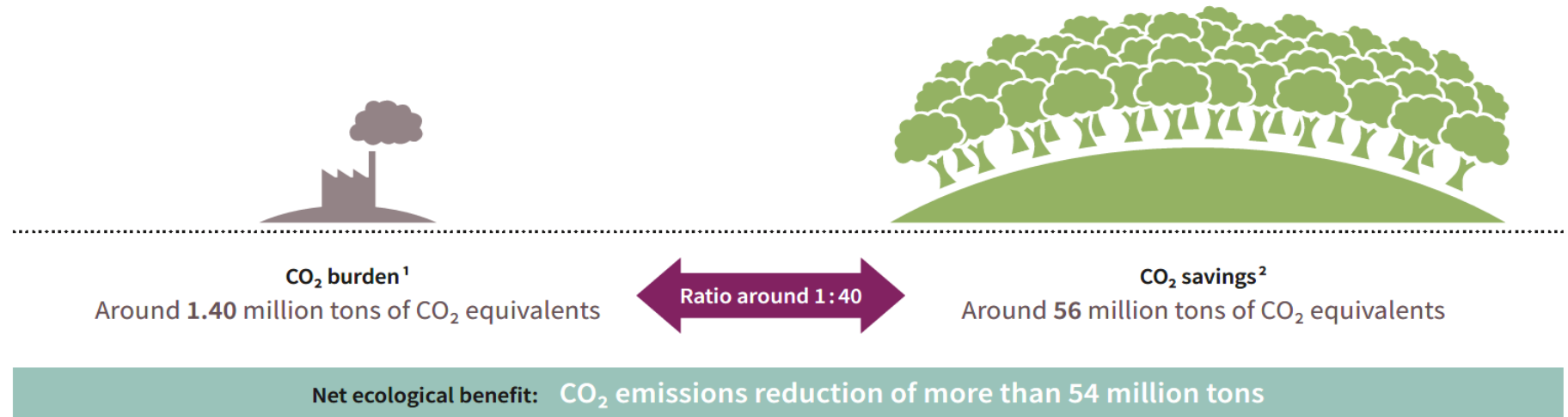
7

ESG: targets & achievements

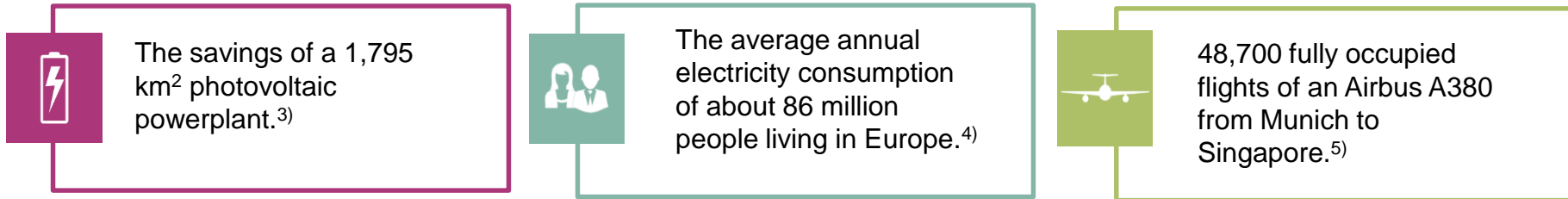
Our products and innovations together with an efficient production are key elements to deal with climate change



We contribute a CO₂ reduction of more than 54 million tons



Our net ecologic CO₂ benefit is equal to...



For footnotes please see appendix

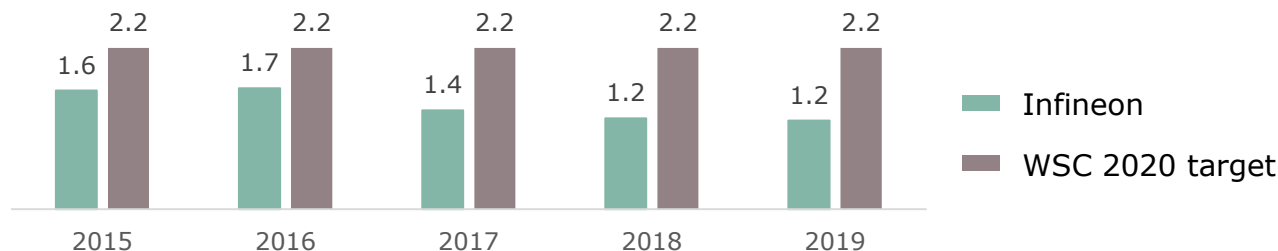
Infineon will become carbon-neutral by 2030

70% CO₂ emissions reduction target in 2025 (Scope 1 and 2 emissions)

1. Avoiding direct emissions and further reducing energy consumption
2. Purchasing green electricity with guarantees of origin for unavoidable emissions
3. Compensate the smallest part by certificates that combine development support and CO₂ abatement

Abatement of Perfluorinated Compounds (PFCs)¹ is one of the most important measures avoiding direct emissions.










Normalized PFC emissions rate in tons of CO₂ equivalent per m² wafer area



Historically, Infineon's normalized emission rate has been below WSC 2020 target of 2.2 tons of CO₂ equivalent per m² wafer area.

1) Namely perfluorinated and polyfluorinated carbon compounds, sulfur hexafluoride (SF₆) and nitrogen trifluoride (NF₃)

External recognitions confirm our engagement in contributing to a sustainable society

		Rating/Score	Scale	Date
	MSCI ESG	AA	CCC to AAA	02/2020
	CDP	B climate scoring B- water scoring	F to A	02/2020
	Ecovadis	98 th percentile “Gold” award	0 to 100	11/2019
	Dow Jones Sustainability Index	79 DJ Sustainability™ World Index listing	0 to 100	09/2019
	Ethibel Sustainability Index Excelence Europe”	Index member	-	09/2019
	ISS-Oekom	C+ Prime Status	D- to A+	07/2019
	FTSE4Good Index	Index member	-	07/2019
	Euronext Vigeo Eurozone 120 Index Euronext Vigeo Europe 120 Index	Indices member	-	06/2019
	Sustainalytics	76 “Outperformer” level	0 to 100	03/2019

Appendix

- 1) This figure considers manufacturing, transportation, function cars, flights, materials, chemicals, water/waste water, direct emissions, energy consumption, waste, etc. and is based on internally collected data and externally available conversion factors. All data relate to the 2019 fiscal year. Manufacturing service providers are not included.
- 2) This figure is based on internally established criteria, which are explained in the explanatory notes. The figure relates to the calendar year 2018 and considers the following fields of application: automotive, LED, induction cookers, server, renewable energy (wind, photovoltaic), mobile phone chargers as well as drives. CO₂ savings are calculated on the basis of potential savings of technologies in which semiconductors are used. The CO₂ savings are allocated on the basis of Infineon market share, semiconductor content and lifetime of the technologies concerned, based on internal and external experts' estimations.
- 3) Calculation based on average polycrystalline photovoltaic cells and the average yearly solar radiation of central Germany.
- 4) Based on the average electricity consumption of private households in Germany and official energy conversion factors.
- 5) Calculation based on average passenger capacity and direct flight route using externally available data and conversion factors.



Part of your life. Part of tomorrow.

Thomas Rosteck, Division President Digital Security Solutions



- › Thomas Rosteck has been the Division President Digital Security Solutions (until September 2018: Chip Card & Security) at Infineon Technologies AG since 2017.
- › Thomas Rosteck was born on 2 March 1966 in Offenbach am Main, Germany. He studied Business Administration and Computer Science at the Technical University of Darmstadt.
- › He joined Infineon in 1998.

Glossary (1 of 2)

AC	alternating current
AC-DC	alternating current - direct current
AD	automated driving
ADAS	advanced driver assistance system
AEB	automatic emergency braking
AFS	advanced frontlight system
AI	artificial intelligence
AR	augmented reality
BEV	battery electric vehicle
BGA	ball grid array
BLE	Bluetooth Low Energy
BoM	bill of material
BT	Bluetooth
CPU	central processing unit
DC	direct current
DC-DC	direct current - direct current

DIY	do it yourself
DPM	digital power management
eCall	emergency call
ECU	electronic control unit
EPS	electric power steering
eSIM	embedded subscriber identity module
EV	electric vehicle
FPGA	field programmable gate array
GPU	graphics processing unit
HEV	mild and full hybrid electric vehicle
HMI	human machine interaction
HSM	hardware security module
HST	high-speed train
HW	hardware
ICE	internal combustion engine
IVN	in-vehicle networking

Glossary (2 of 2)

IPM	intelligent power module
iPol	image processing line
IRF	International Rectifier
LSEV	low-speed electric vehicle
LSPS	LS Power Semitech Co. Ltd.
μC	microcontroller
MEMS	micro electro-mechanical systems
MHA	major home appliances
MIMO	multiple input, multiple output
micro-hybrid	vehicles using start-stop systems and limited recuperation
mild-hybrid	vehicles using start-stop systems, recuperation, DC-DC conversion, e-motor
MOSFET	metal-oxide silicon field-effect transistor
OBC	on-board charger
OEM	original equipment manufacturer
PHEV	plug-in hybrid electric vehicle
Pol	point-of-load

PV	photovoltaic
PSoC	programmable system-on-chip
RF	radio frequency
rhs	right-hand scale
Si	silicon
SiC	silicon carbide
SiGe	silicon germanium
SMPS	switch-mode power supply
SNR	signal-to-noise ratio
SOTA	software over-the-air
SRAM	static random access memory
SW	software
ToF	time-of-flight
TPM	trusted platform module
UPS	uninterruptible power supply
V2X	vehicle-to-everything communication
VR	virtual reality
VSD	variable speed drive
xEV	all degrees of vehicle electrification (EV, HEV, PHEV)

Disclaimer

Disclaimer

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Deutscher Zukunftspreis 2015, laureate Infineon, photographer Ansgar Pudenz, Hamburg (Germany).

Financial calendar

Date	Location	Event
3 – 4 Jun 2020	Berlin → virtual	dbAccess Berlin Conference
9 – 10 Jun 2020	Paris → virtual	Exane 22 nd European CEO Conference
4 Aug 2020*		Q3 FY20 Results
21 Sep 2020	Unterschleißheim (nearby Munich)	Berenberg Goldman Sachs German Corporate Conference
22 Sep 2020	Munich	Baader Investment Conference
6 Oct 2020		Call: ATV Business Update
9 Nov 2020*		Q4 FY20 and FY 2020 Results

* preliminary

Most recent presentations

ATV Call
Peter Schiefer
8 October 2019



https://www.infineon.com/atv_call

IPC Business Update
Dr. Peter Wawer, Dr. Peter Friedrichs
7 May 2020



https://www.infineon.com/pcim_presentaion

IFX Day 2018
Capital Markets Day
London, 12 June 2018



https://www.infineon.com/ifxday_2018

Sustainability Report 2019
23 November 2019



https://www.infineon.com/sustainability_2019

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